



SN74LS166 (LX)

8-bit parallel-in/serial out shift register

Product Specification

Specification Revision History:

Version	Date	Description
2023-10-A0	2023-10	New
2023-11-A1	2023-11	Parameter modification



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灵星芯微 用芯精英

深圳市灵星芯微电子科技有限公司

Shenzhen Lingxing Microelectronics Technology Co., Ltd.

Tab: 835-12-B4

Number: SN74LS166-AX-LJ-A102EN

1、General Description

The SN74LS166 is an 8-bit serial or parallel-in/serial-out shift register.

Features:

- Temperature range: -40°C to +125°C
- Packaging information: DIP16/SOP16/TSSOP16

**Ordering Information:****Tube packing specifications:**

Part number	Packaging form	Marking code	Tube quantity	Boxed tube quantity	Boxed quantity	Notes
SN74LS166AN(LX)	DIP16	SN74LS166AN	25 PCS/tube	40 tube/box	1000 PCS/box	Dimensions of plastic enclosure: 19.0mm×6.4mm Pin spacing: 2.54mm
SN74LS166AD(LX)	SOP16	LS166A	50 PCS/tube	200 tube/box	10000 PCS/box	Dimensions of plastic enclosure: 10.0mm×3.9mm Pin spacing: 1.27mm
SN74LS166PW(LX)	TSSOP16	LS166	96 PCS/tube	200 tube/box	19200 PCS/box	Dimensions of plastic enclosure: 5.0mm×4.4mm Pin spacing: 0.65mm

**Reel packing specifications:**

Part number	Packaging form	Marking code	Reel quantity	Boxed reel quantity	Notes
SN74LS166ADR(LX)	SOP16	LS166A	2500 PCS/reel	5000 PCS/box	Dimensions of plastic enclosure: 10.0mm×3.9mm Pin spacing: 1.27mm
SN74LS166PW(LX)	TSSOP16	LS166	5000 PCS/reel	10000 PCS/box	Dimensions of plastic enclosure: 5.0mm×4.4mm Pin spacing: 0.65mm

Note : If the physical information is inconsistent with the ordering information, please refer to the actual product.



2、Block Diagram And Pin Description

2.1、Block Diagram

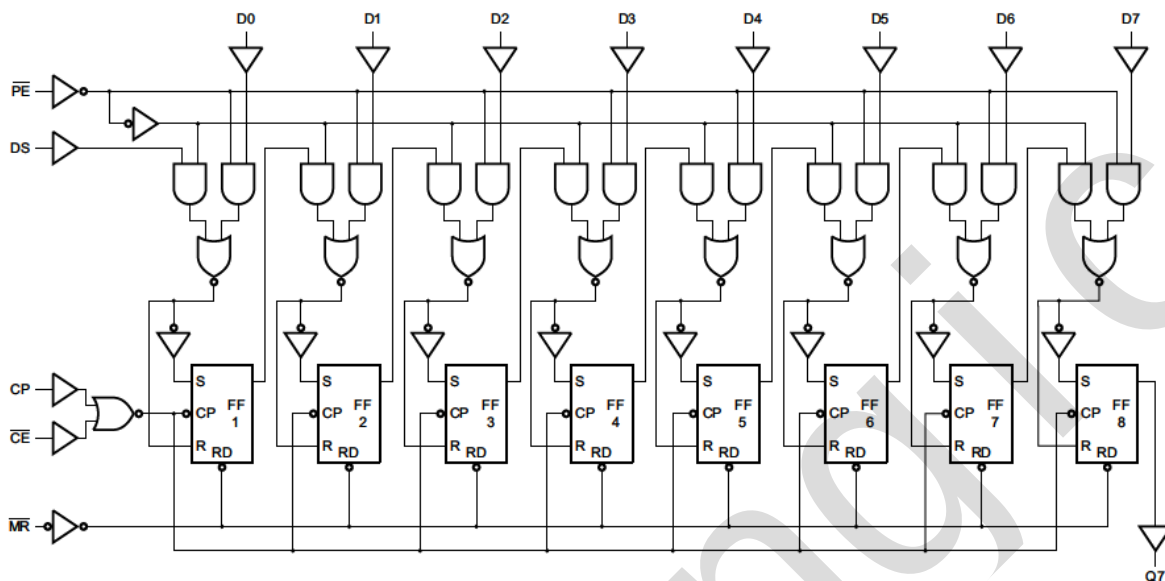
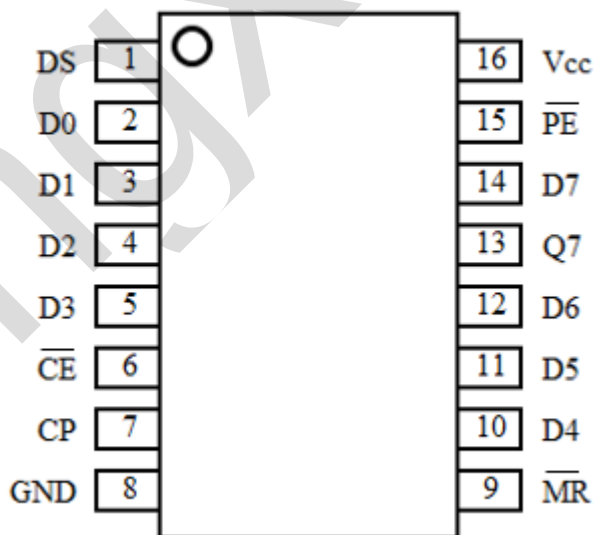


Figure 1. Logic symbol

2.2、Pin Configurations





2.3、Pin Description

Pin No.	Pin Name	Description
1	DS	serial data input
2	D0	parallel data input
3	D1	parallel data input
4	D2	parallel data input
5	D3	parallel data input
6	$\overline{\text{CE}}$	clock enable input (active LOW)
7	CP	clock input (LOW-to-HIGH edge-triggered)
8	GND	ground (0V)
9	$\overline{\text{MR}}$	asynchronous master reset (active LOW)
10	D4	parallel data input
11	D5	parallel data input
12	D6	parallel data input
13	Q7	serial output from the last stage
14	D7	parallel data input
15	$\overline{\text{PE}}$	parallel enable input (active LOW)
16	V _{CC}	supply voltage

2.4、Function Table

Operating modes	Inputs					Qn registers		Output
	$\overline{\text{PE}}$	$\overline{\text{CE}}$	CP	DS	D0 to D7	Q0	Q1 to Q6	Q7
parallel load	l	l	↑	X	l	L	L to L	L
	l	l	↑	X	h	H	H to H	H
serial shift	h	l	↑	l	X	L	q0 to q5	q6
	h	l	↑	h	X	H	q0 to q5	q6
hold “do nothing”	X	H	X	X	X	q0	q1 to q6	q7

Note:

H = HIGH voltage level;

h = HIGH voltage level one set-up time prior to the LOW-to-HIGH clock transition;

L = LOW voltage level;

l = LOW voltage level one set-up time prior to the LOW-to-HIGH clock transition;

q = state of the referenced output one set-up time prior to the LOW-to-HIGH clock transition;

X = don't care;

↑ = LOW-to-HIGH clock transition.



3、Electrical Parameter

3.1、Absolute Maximum Ratings

(Voltages are referenced to GND (ground=0V), unless otherwise specified.)

Parameter	Symbol	Conditions	Min.	Max.	Unit
supply voltage	V_{CC}	-	-0.5	+7	V
supply current	I_{CC}	-	-	50	mA
ground current	I_{GND}	-	-50	-	mA
input clamping current	I_{IK}	$V_I < -0.5V$ or $V_I > V_{CC}+0.5V$	-	± 20	mA
output clamping current	I_{OK}	$V_O < -0.5V$ or $V_O > V_{CC}+0.5V$	-	± 20	mA
output current	I_O	$-0.5V < V_O < V_{CC}+0.5V$	-	± 25	mA
storage temperature	T_{stg}	-	-65	+150	°C
soldering temperature	T_L	10s	DIP	245	°C
			SOP/TSSOP	260	

3.2、Recommended Operating Conditions

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
supply voltage	V_{CC}	-	2.0	5.0	6.0	V
input voltage	V_I	-	0	-	V_{CC}	V
output voltage	V_O	-	0	-	V_{CC}	V
ambient temperature	T_{amb}	-	-40	-	+125	°C



3.3、Electrical Characteristics

3.3.1、DC Characteristics 1

($T_{amb} = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$, voltages are referenced to GND (ground=0V), unless otherwise specified.)

Parameter	Symbol	V_{CC}	Conditions	Min.	Typ.	Max.	Unit
HIGH-level input voltage	V_{IH}	2.0V	-	1.5	1.2	-	V
		4.5V	-	3.15	2.4	-	V
		6.0V	-	4.2	3.2	-	V
LOW-level input voltage	V_{IL}	2.0V	-	-	0.8	0.5	V
		4.5V	-	-	2.1	1.35	V
		6.0V	-	-	2.8	1.8	V
HIGH-level output voltage	V_{OH}	2.0V	$I_O = -20\mu\text{A}$	1.9	2.0	-	V
		4.5V	$I_O = -20\mu\text{A}$	4.4	4.5	-	V
		6.0V	$I_O = -20\mu\text{A}$	5.9	6.0	-	V
		4.5V	$I_O = -4.0\text{mA}$	3.84	4.32	-	V
		6.0V	$I_O = -5.2\text{mA}$	5.34	5.81	-	V
LOW-level output voltage	V_{OL}	2.0V	$I_O = 20\mu\text{A}$	-	0	0.1	V
		4.5V	$I_O = 20\mu\text{A}$	-	0	0.1	V
		6.0V	$I_O = 20\mu\text{A}$	-	0	0.1	V
		4.5V	$I_O = 4.0\text{mA}$	-	0.15	0.33	V
		6.0V	$I_O = 5.2\text{mA}$	-	0.16	0.33	V
input leakage current	I_I	6.0V	$V_I = V_{CC}$ or GND	-	-	± 1	μA
supply current	I_{CC}	6.0V	$V_I = V_{CC}$ or GND; $I_O = 0\text{A}$	-	-	80	μA



3.3.2、DC Characteristics 2

($T_{amb} = -40^{\circ}\text{C}$ to $+125^{\circ}\text{C}$, voltages are referenced to GND (ground=0V), unless otherwise specified.)

Parameter	Symbol	V_{CC}	Conditions	Min.	Typ.	Max.	Unit
HIGH-level input voltage	V_{IH}	2.0V	-	1.5	-	-	V
		4.5V	-	3.15	-	-	V
		6.0V	-	4.2	-	-	V
LOW-level input voltage	V_{IL}	2.0V	-	-	-	0.5	V
		4.5V	-	-	-	1.35	V
		6.0V	-	-	-	1.8	V
HIGH-level output voltage	V_{OH}	2.0V	$I_O = -20\mu\text{A}$	1.9	-	-	V
		4.5V	$I_O = -20\mu\text{A}$	4.4	-	-	V
		6.0V	$I_O = -20\mu\text{A}$	5.9	-	-	V
		4.5V	$I_O = -4.0\text{mA}$	3.7	-	-	V
		6.0V	$I_O = -5.2\text{mA}$	5.2	-	-	V
LOW-level output voltage	V_{OL}	2.0V	$I_O = 20\mu\text{A}$	-	-	0.1	V
		4.5V	$I_O = 20\mu\text{A}$	-	-	0.1	V
		6.0V	$I_O = 20\mu\text{A}$	-	-	0.1	V
		4.5V	$I_O = 4.0\text{mA}$	-	-	0.4	V
		6.0V	$I_O = 5.2\text{mA}$	-	-	0.4	V
input leakage current	I_I	6.0V	$V_I = V_{CC}$ or GND	-	-	± 1	μA
supply current	I_{CC}	6.0V	$V_I = V_{CC}$ or GND; $I_O = 0\text{A}$	-	-	160	μA



3.3.3、AC Characteristics 1

($T_{amb} = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$, voltages are referenced to GND (ground=0V), unless otherwise specified.)

Parameter	Symbol	V_{CC}	Conditions	Min.	Typ.	Max.	Unit
CP to Q7 propagation delay	t_{PLH}, t_{PHL}	2.0V	$C_L = 50\text{pF}$	-	50	190	ns
		4.5V	$C_L = 50\text{pF}$	-	18	38	ns
		5.0V	$C_L = 15\text{pF}$	-	15	-	ns
		6.0V	$C_L = 50\text{pF}$	-	14	33	ns
$\overline{\text{MR}}$ to Q7 propagation delay	t_{PLH}, t_{PHL}	2.0V	$C_L = 50\text{pF}$	-	47	200	ns
		4.5V	$C_L = 50\text{pF}$	-	17	40	ns
		5.0V	$C_L = 15\text{pF}$	-	14	-	ns
		6.0V	$C_L = 50\text{pF}$	-	14	34	ns
transition time	t_{THL}, t_{TLH}	2.0V	$C_L = 50\text{pF}$	-	19	95	ns
		4.5V	$C_L = 50\text{pF}$	-	7	19	ns
		6.0V	$C_L = 50\text{pF}$	-	6	16	ns
CP input HIGH or LOW pulse width	t_w	2.0V	$C_L = 50\text{pF}$	100	17	-	ns
		4.5V	$C_L = 50\text{pF}$	20	6	-	ns
		6.0V	$C_L = 50\text{pF}$	17	5	-	ns
$\overline{\text{MR}}$ input LOW pulse width	t_w	2.0V	$C_L = 50\text{pF}$	125	25	-	ns
		4.5V	$C_L = 50\text{pF}$	25	9	-	ns
		6.0V	$C_L = 50\text{pF}$	21	7	-	ns
$\overline{\text{MR}}$ to CP recovery time	t_{rec}	2.0V	$C_L = 50\text{pF}$	0	-19	-	ns
		4.5V	$C_L = 50\text{pF}$	0	-7	-	ns
		6.0V	$C_L = 50\text{pF}$	0	-6	-	ns
Dn, $\overline{\text{CE}}$ to CP set_up time	t_{su}	2.0V	$C_L = 50\text{pF}$	100	14	-	ns
		4.5V	$C_L = 50\text{pF}$	20	5	-	ns
		6.0V	$C_L = 50\text{pF}$	17	4	-	ns
$\overline{\text{PE}}$ to CP set_up time	t_{su}	2.0V	$C_L = 50\text{pF}$	125	33	-	ns
		4.5V	$C_L = 50\text{pF}$	25	12	-	ns
		6.0V	$C_L = 50\text{pF}$	21	10	-	ns
Dn, $\overline{\text{CE}}$ to CP hold time	t_h	2.0V	$C_L = 50\text{pF}$	2	-8	-	ns
		4.5V	$C_L = 50\text{pF}$	2	-3	-	ns
		6.0V	$C_L = 50\text{pF}$	2	-2	-	ns
$\overline{\text{PE}}$ to CP hold time	t_h	2.0V	$C_L = 50\text{pF}$	0	-28	-	ns
		4.5V	$C_L = 50\text{pF}$	0	-10	-	ns
		6.0V	$C_L = 50\text{pF}$	0	-8	-	ns
maximum frequency	f_{max}	2.0V	$C_L = 50\text{pF}$	4.8	19	-	MHZ
		4.5V	$C_L = 50\text{pF}$	24	57	-	MHZ
		5.0V	$C_L = 15\text{pF}$	-	63	-	MHZ
		6.0V	$C_L = 50\text{pF}$	28	68	-	MHZ



3.3.4、AC Characteristics 2

($T_{amb} = -40^{\circ}\text{C}$ to $+125^{\circ}\text{C}$, voltages are referenced to GND (ground=0V), unless otherwise specified.)

Parameter	Symbol	V _{CC}	Conditions	Min.	Typ.	Max.	Unit
CP to Q7 propagation delay	t_{PLH}, t_{PHL}	2.0V	$C_L=50\text{pF}$	-	-	225	ns
		4.5V	$C_L=50\text{pF}$	-	-	45	ns
		6.0V	$C_L=50\text{pF}$	-	-	38	ns
$\overline{\text{MR}}$ to Q7 propagation delay	t_{PLH}, t_{PHL}	2.0V	$C_L=50\text{pF}$	-	-	240	ns
		4.5V	$C_L=50\text{pF}$	-	-	48	ns
		6.0V	$C_L=50\text{pF}$	-	-	41	ns
transition time	t_{THL}, t_{TLH}	2.0V	$C_L=50\text{pF}$	-	-	110	ns
		4.5V	$C_L=50\text{pF}$	-	-	22	ns
		6.0V	$C_L=50\text{pF}$	-	-	19	ns
CP input HIGH or LOW pulse width	t_w	2.0V	$C_L=50\text{pF}$	120	-	-	ns
		4.5V	$C_L=50\text{pF}$	24	-	-	ns
		6.0V	$C_L=50\text{pF}$	20	-	-	ns
$\overline{\text{MR}}$ input LOW pulse width	t_w	2.0V	$C_L=50\text{pF}$	150	-	-	ns
		4.5V	$C_L=50\text{pF}$	30	-	-	ns
		6.0V	$C_L=50\text{pF}$	26	-	-	ns
$\overline{\text{MR}}$ to CP recovery time	t_{rec}	2.0V	$C_L=50\text{pF}$	0	-	-	ns
		4.5V	$C_L=50\text{pF}$	0	-	-	ns
		6.0V	$C_L=50\text{pF}$	0	-	-	ns
Dn, $\overline{\text{CE}}$ to CP set_up time	t_{su}	2.0V	$C_L=50\text{pF}$	120	-	-	ns
		4.5V	$C_L=50\text{pF}$	24	-	-	ns
		6.0V	$C_L=50\text{pF}$	20	-	-	ns
$\overline{\text{PE}}$ to CP set_up time	t_{su}	2.0V	$C_L=50\text{pF}$	150	-	-	ns
		4.5V	$C_L=50\text{pF}$	30	-	-	ns
		6.0V	$C_L=50\text{pF}$	26	-	-	ns
Dn, $\overline{\text{CE}}$ to CP hold time	t_h	2.0V	$C_L=50\text{pF}$	2	-	-	ns
		4.5V	$C_L=50\text{pF}$	2	-	-	ns
		6.0V	$C_L=50\text{pF}$	2	-	-	ns
$\overline{\text{PE}}$ to CP hold time	t_h	2.0V	$C_L=50\text{pF}$	0	-	-	ns
		4.5V	$C_L=50\text{pF}$	0	-	-	ns
		6.0V	$C_L=50\text{pF}$	0	-	-	ns
maximum frequency	f_{max}	2.0V	$C_L=50\text{pF}$	4	-	-	MHZ
		4.5V	$C_L=50\text{pF}$	20	-	-	MHZ
		6.0V	$C_L=50\text{pF}$	24	-	-	MHZ



4、Testing Circuit

4.1、AC Testing Circuit

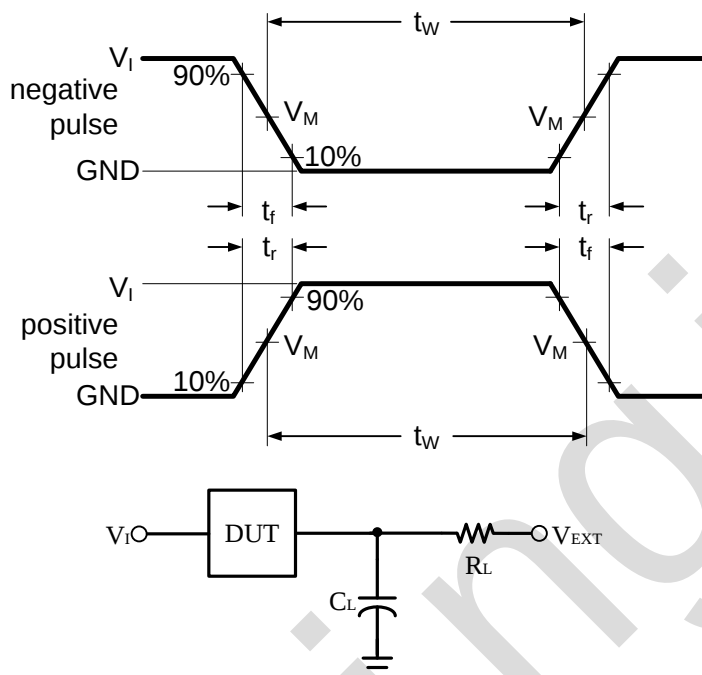


Figure 3. Test circuit for measuring switching times

C_L includes probe and jig capacitance.

4.2、Test Data

Input		Load		V_{EXT}		
V_I	$t_r = t_f$	C_L	R_L	t_{PLH}/t_{PHL}	t_{PLZ}/t_{PZL}	t_{PHZ}/t_{PZH}
V_{CC}	3.0ns	15pF, 50pF	1K Ω	Open	V_{CC}	GND

4.3、AC Testing Waveforms

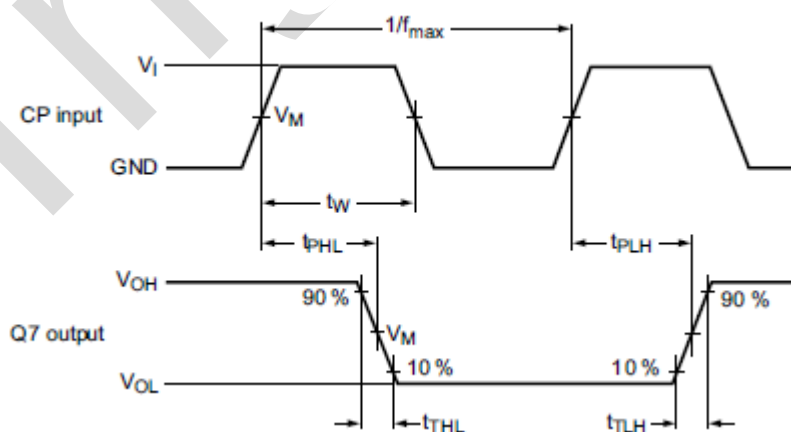


Figure 4. Clock (CP) to output (Q7) propagation delays, pulse width, output transition times and maximum frequency

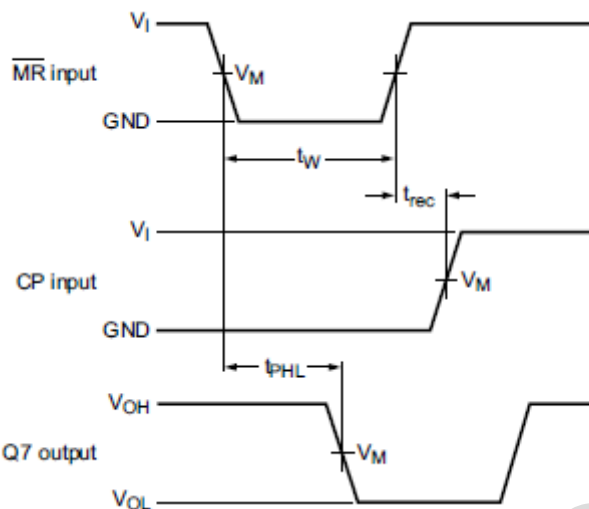


Figure 5. Master reset ($\overline{\text{MR}}$) pulse width, $\overline{\text{MR}}$ to output (Q7) propagation delay and $\overline{\text{MR}}$ to clock (CP) recovery time

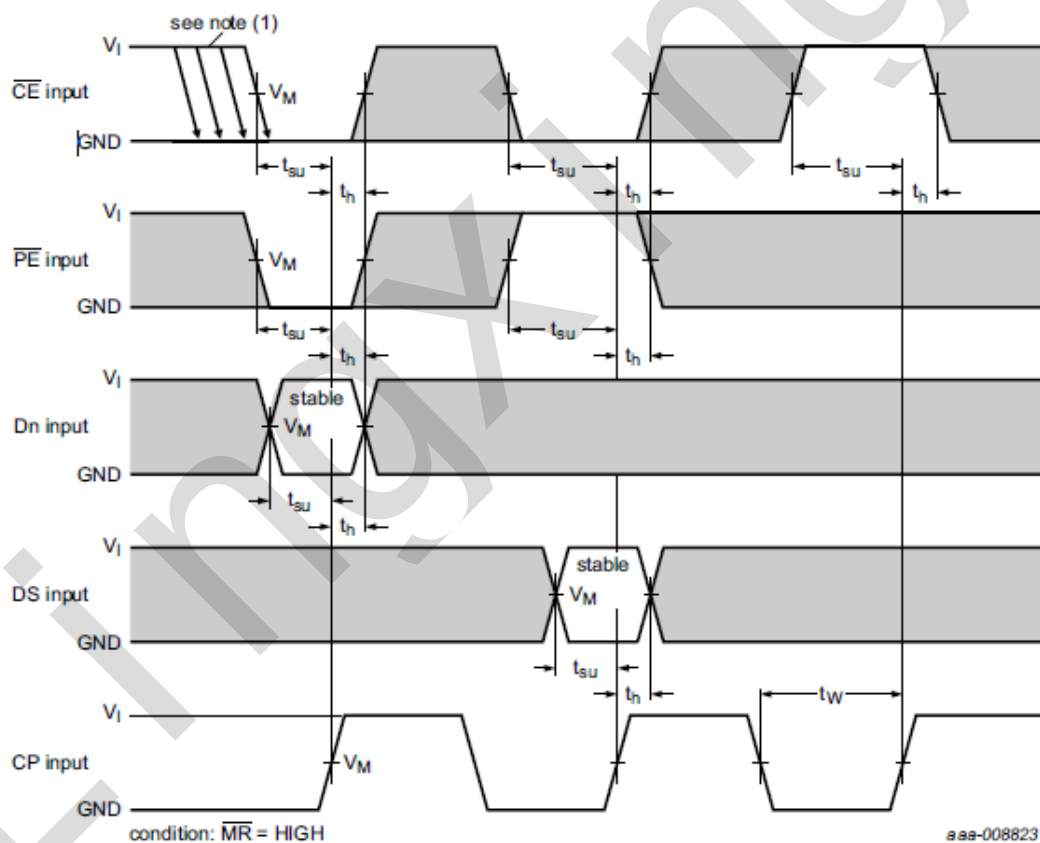


Figure 6. Set-up and hold times



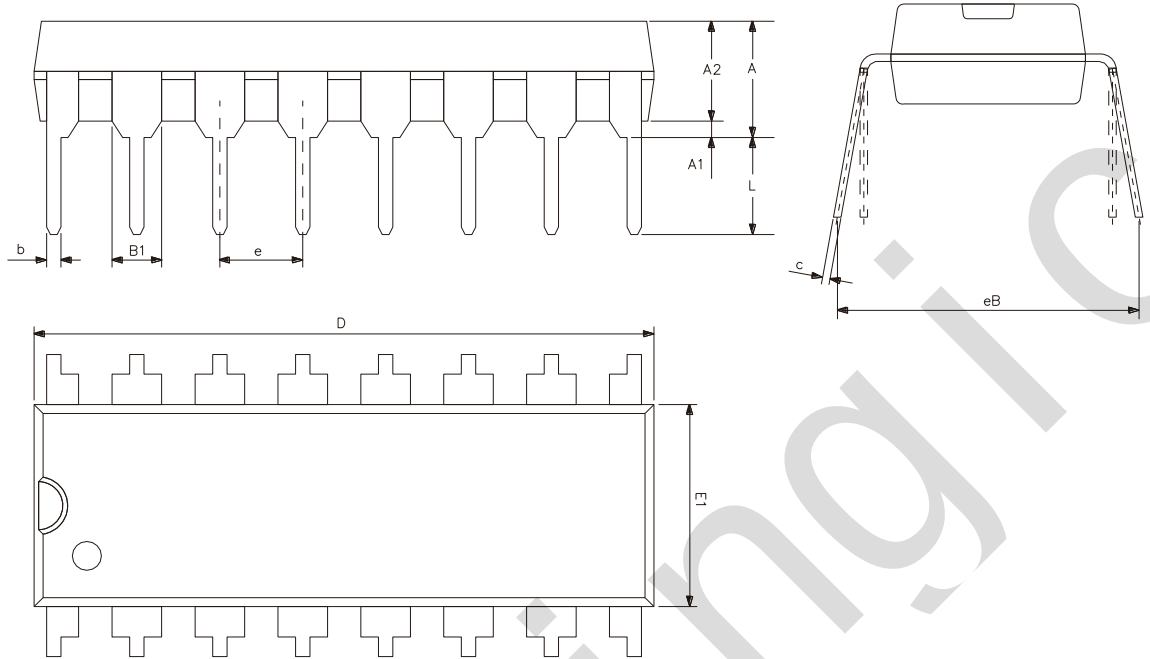
4.4、Measurement Points

Input	Output
V_M	V_M
$0.5 \times V_{CC}$	$0.5 \times V_{CC}$



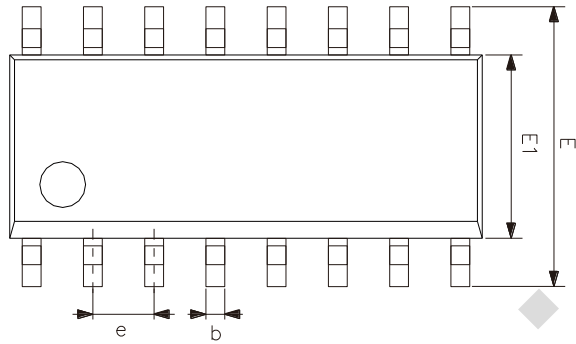
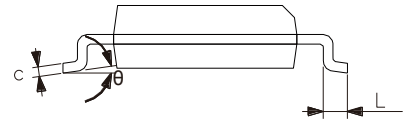
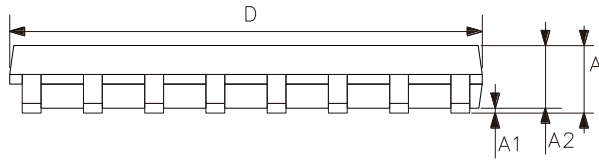
5、Package Information

5.1、DIP16



Symbol	Dimensions (mm)	
	Min.	Max.
A2	3.20	3.60
A1	0.51	-
A	3.60	5.33
L	3.00	3.60
b	0.36	0.56
B1	1.52	
D	18.80	19.94
E1	6.20	6.60
e	2.54	
c	0.20	0.36
eB	7.62	9.30

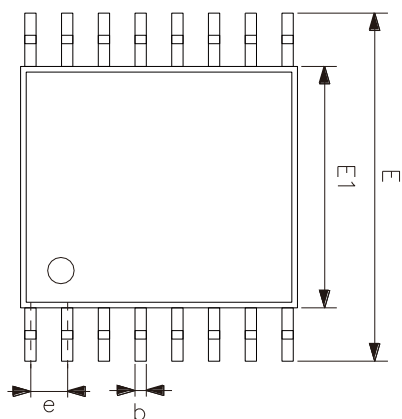
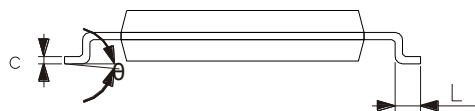
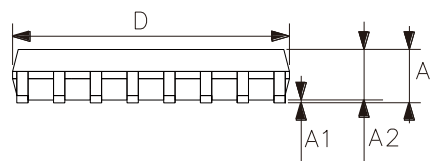
5.2、SOP16



Symbol	Dimensions (mm)	
	Min.	Max.
A	1.35	1.80
A1	0.10	0.25
A2	1.25	1.55
b	0.33	0.51
c	0.19	0.25
D	9.50	10.10
E	5.80	6.30
E1	3.70	4.10
e	1.27	
L	0.35	0.89
θ	0°	8°



5.3、TSSOP16



Symbol	Dimensions (mm)	
	Min.	Max.
A	-	1.20
A1	0.05	0.15
A2	0.80	1.05
b	0.19	0.30
c	0.09	0.20
D	4.90	5.10
E1	4.30	4.50
E	6.20	6.60
e	0.65	
L	0.45	0.75
θ	0°	8°



6、Statements And Notes

6.1、The name and content of Hazardous substances or Elements in the product

Part name	Hazardous substances or Elements									
	Lead and lead compounds	Mercury and mercury compounds	Cadmium and cadmium compounds	Hexavalent chromium compounds	Polybrominated biphenyls	Polybrominated biphenyl ethers	Dibutyl phthalate	Butylbenzyl phthalate	Di-2-ethylhexyl phthalate	Diisobutyl phthalate
Lead frame	○	○	○	○	○	○	○	○	○	○
Plastic resin	○	○	○	○	○	○	○	○	○	○
Chip	○	○	○	○	○	○	○	○	○	○
The lead	○	○	○	○	○	○	○	○	○	○
Plastic sheet installed	○	○	○	○	○	○	○	○	○	○
explanation	○: Indicates that the content of hazardous substances or elements in the detection limit of the following the SJ/T11363-2006 standard. ×: Indicates that the content of hazardous substances or elements exceeding the SJ/T11363-2006 Standard limit requirements.									

6.2、Notes

We recommend you to read this chapter carefully before using this product.

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This product is not suitable for critical equipment such as life-saving, life-sustaining or safety equipment. It is also not suitable for applications that may result in personal injury, death, or serious property or environmental damage due to product malfunction or failure. Lingxing will not be liable for any damages incurred by the customers at their own risk for such applications.

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